502697229 02/26/2014

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2743834

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
ARITO OGAWA	02/19/2014
TSUYOSHI TAKEDA	02/19/2014

RECEIVING PARTY DATA

Name:	HITACHI KOKUSAI ELECTRIC INC.
Street Address:	14-1, SOTOKANDA 4-CHOME
Internal Address:	CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	1018980

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14190574

CORRESPONDENCE DATA

 Fax Number:
 (215)568-6499

 Phone:
 215-568-6400

 Email:
 ppetaccia@vklaw.com

Correspondence will be sent via US Mail when the email attempt is unsuccessful.

Correspondent Name: KEIKO KIMURA MIDDLETON Address Line 1: VOLPE AND KOENIG, P.C.

Address Line 2: 30 SOUTH 17TH STREET, STE. 1800
Address Line 4: PHILADELPHIA, PENNSYLVANIA 19103

ATTORNEY DOCKET NUMBER:	HITACHI13-21010279US02
NAME OF SUBMITTER:	KEIKO KIMURA MIDDLETON
Signature:	/KEIKO KIMURA MIDDLETON/
	PATENT

502697229 REEL: 032303 FRAME: 0305

Date:	02/26/2014
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 4 source=Assignment_HITACHI13_21010279 source=Assignment_HITACHI13_21010279 source=Assignment_HITACHI13_21010279 source=Assignment_HITACHI13_21010279	US02#page2.tif US02#page3.tif

PATENT REEL: 032303 FRAME: 0306

ASSIGNMENT AND DECLARATION

With respect to the invention titled

METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, METHOD OF PROCESSING SUBSTRATE, SUBSTRATE PROCESSING APPARATUS AND COMPUTER-READABLE RECORDING MEDIUM

for which the undersigned has authorized or prepared an application for United States Letters Patent, U.S. Patent Application No. 14/190,574 filed on February 26, 2014

I (the undersigned) hereby state the following.

DECLARATION

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than 5 years, or both.

ASSIGNMENT

The undersigned hereby authorizes assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

Assignee

HITACHI KOKUSAI ELECTRIC INC.

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Atty. Docket No.

Assignee	State	\mathbf{or}	Country
of Incorp	oratio	n	

Japan

Assignee Address

14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan

Assignee is desirous of acquiring the entire right, title and interest in the invention, all applications for and all letters patent issued on the invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee and assignee's successors, assigns and legal representatives the entire right, title and interest in the invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, and all divisions and continuations thereof, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of the invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of the assignee, and to execute all instruments proper to carry out the intent of this instrument.

The undersigned warrants that the rights and property herein conveyed are free and clear of any encumbrance.

AND this Assignment may be executed in multiple counterparts, each of which shall be deemed to be an original of this Assignment. Additionally, the undersigned hereby authorizes our attorneys to collect the signature pages of each executed counterpart and to attach those signature pages to a single copy of this instrument, which single copy and attached signature pages together shall constitute an original of this Assignment.

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SIGNATURE SHEET FOR DECLARATION AND ASSIGNMENT

Inventor's Name	OGAWA, Arito	<u>.</u>
Inventor's Signature	Avito Oganos	
Date _	Avito Oganos February 19. 2014	_
Signed at	Toyama-shi, Japan	• •
_	(City and Country)	-
STATEME	ENT OF WITNESS (optional):	
	Ι,	
	Name of Witness	
was perso	nally present and did see OGAWA, Arito	
	inventor identified above	
execute th	nis Assignment on and such Assignor is per-	sonally known
to me to be	e the person described herein.	
Witness Signature		
must accom	tion data sheet (PTO/SB/14 or equivalent), including naming the entire in apany this form. Use a separate form for each inventor; or check the e attached page(s) to list additional inventors.	

 \blacksquare Additional inventors are being named on the $\underline{1}$ supplemental sheet(s) attached hereto.

SUPPLEMENTAL SHEET FOR DECLARATION AND ASSIGNMENT

Inventor's Name	TAKEDA, Tsuyoshi	
Inventor's Signature	一 河 图 烟9	·············
Date	Feb 19, 2014	
Signed at	Toyama-shi, Japan	
,	(City and Country)	***********
STATEMI	IENT OF WITNESS (optional):	
	. I.	
	Name of Witness	
was perso	onally present and did see TAKEDA, Tsuyoshi	
	inventor identified above	
execute th	this Assignment on and such Assignor is p	ersonally know
to me to b	be the person described herein.	
Witness Signature		

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PATENT REEL: 032303 FRAME: 0310